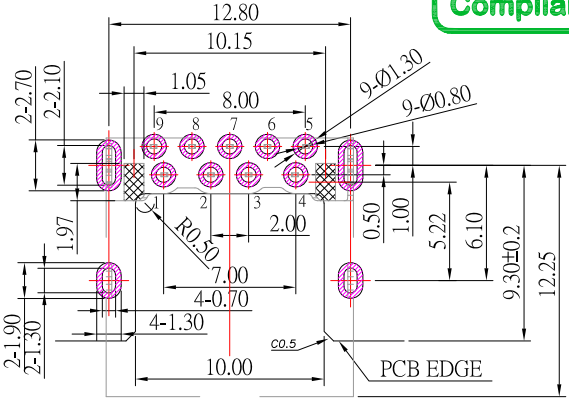




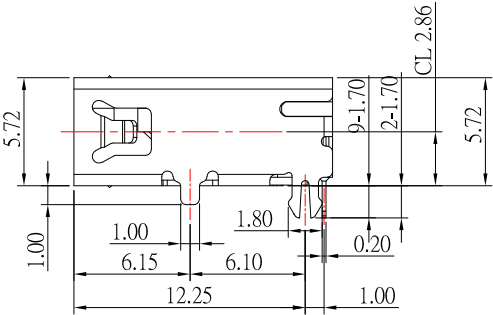
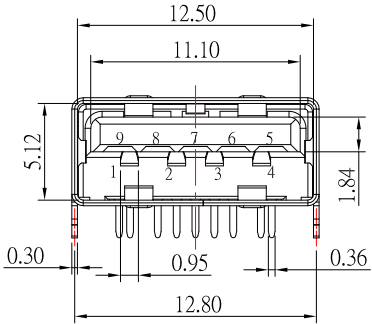
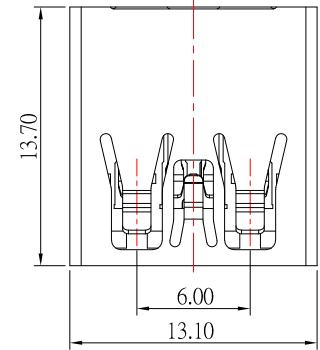
SUA-110H24-30xx-S277

鍍層厚度 :	COLOR :
Blank : 1u"	BLUE : Blank
2 : 15u"	Black : B
3 : 30u"	Red : R

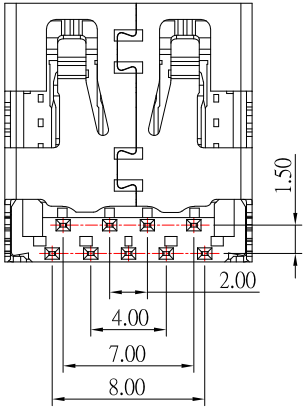


RECOMMENDED PCB LAYOUT
(TOP VIEW)

- NOTE:
- MATERIAL:
 - Housing: LCP,(UL94V-0)
 - Contact: Phosphor Bronze
 - Shell: SUS
 - Finish:
 - Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
 - Shell: Nickel under Plated surface layer
 - SPECIFICATION:
 - Current Rate: 1.5 A
 - insulator Resistance:100M Ω Min
 - Dielectric Strength: 100V AC
 - Contact Resistance: 30m Ω Max
 - Operation Temperature: -25°C ~ +75°C
 - Insertion Force: 35 N
 - Extraction Force: 10 N



Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE	
1	VBUS	POWER	SECOND	
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD	
3	D+			
4	GND	GROUND FOR POWER RETURN	SECOND	
5	StdA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR	LAST	
6	StdA_SSRX+			
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	FRIST	
8	StdA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR		
9	StdA_SSTX+			
Shell	Shield	CONNECTOR METAL SHELL		



6	更新圖面	Jack	082824
5	更新pcb layout	Jack	030520
4	新增pcb layout尺寸	Jack	101619
3	更新pcb layout	Jack	092618
2	更新為A0版	Jack	051617
1	更新尺寸6.6改6.1	Jack	040715
ITEM NO.	DESCRIPTION	DRAWN	DATE

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :	Up to 5 Above 5 ~ 15 Above 15 ~ 30 Above 30 ~ 50 Angle	±0.2 ±0.3 ±0.4 ±0.5 ±0.3°	3RD. ANGEL'S		UNITS	MM
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DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	08/28/24	FINISH	MODLE	USB A/F DIP R/A TYPE
CHECKED BY:	DATE	SCALE	DWG NO.	SUA-110H24-30xx-S277
Jacky Chen	08/28/24	1 : 1	PART NO.	SUA-110H24-30xx-S277
APPROVED BY:	DATE	SHEET NO.	1 of 1	VER R6
Tony Kao	08/28/24			